

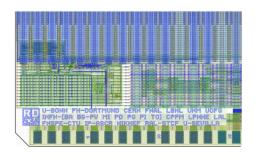
MARCH 2021

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RD53A PIXEL CHIP



RD53A Specificat	ions
Technology	TSMC 65 nm CMOS
Pixel size	$50 \times 50 \ \mu m^2$
Chip size	20 × 11.8 mm ² Half size of the final CMS chip
Number of pixels	$400 \times 192 = 76800$ Final CMS chip: $432 \times 336 = 145152$
Detector capacitance	< 100 fF
Leakage current	< 10 nA
(In-time) threshold	(1200e ⁻) 600e ⁻
Noise hits	< 10-6
Radiation tolerance	500 Mrad at -12°C
Temperature	[- 40°C; +40°C]







Top test pad

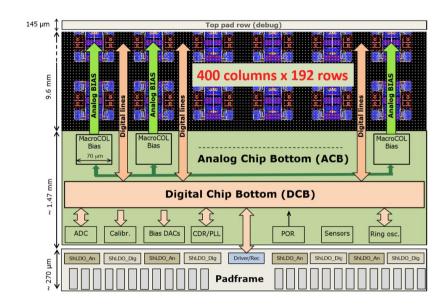
- Row of test pads for debugging purposes
- Will be removed in the production chip

Pixel matrix

• $192 \times 400 = 76800$ pixels

Chip Bottom

 all global analog and digital circuitry needed to bias, configure, monitor and readout the chip





Top test pad

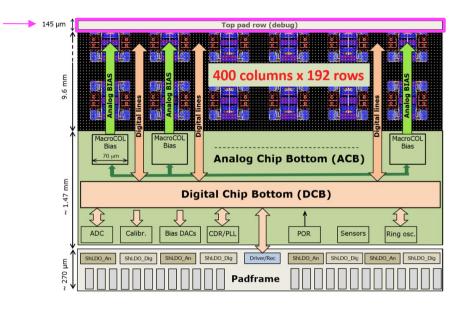
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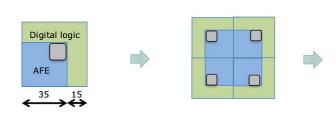
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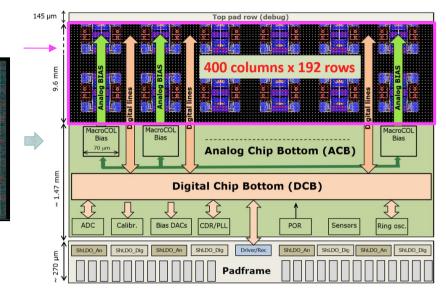
Chip Bottom

 all global analog and digital circuitry needed to bias, configure, monitor and readout the chip









Pixel

50% Analog 50% Digital + Bump pad

Analog island

2×2 pixel quad

Pixel core

in a fully
synthetized
digital sea

Pixel matrix

All cores the same



Power distribution

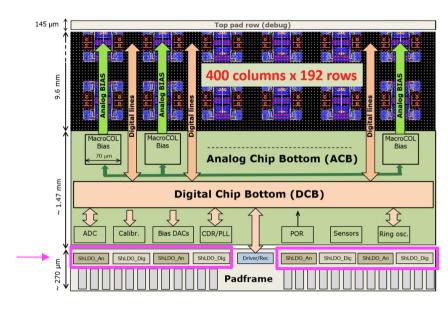
 Power lines distributed from the bottom to the whole chip

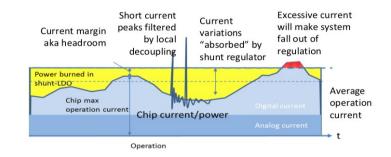
Serial powering

- Baseline powering scheme for CMS and ATLAS
 HL-LHC pixel detectors
- Pixel modules powered in series (chips in a module powered in parallel)

Shunt-LDO regulator

- 2 Shunt-LDO regulators
 (1 analog + 1 digital)
- supply constant input current independent of the load
- excess current is shunted to ground (headroom)







Analog chip bottom (ACB)

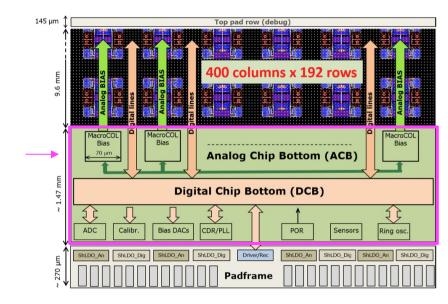
- Providing current reference DACs (I_{ref}) and voltage levels to the calibration injection circuit
- Monitoring: temperature, radiation, currents, voltages
- CDR/PLL recovers data and clock from input stream at 160 Mbps

Digital chip bottom (DCB)

- Control and processing functionalities
- Input, Output and Configuration digital logic

Output Serializer & CML cable drivers

- 4 Aurora lanes at 1.28 Gbps
- CML output driver with programmable preemphasis



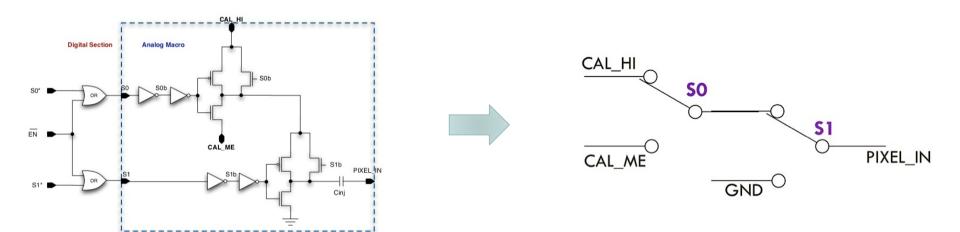
CALIBRATION INJECTION CIRCUIT



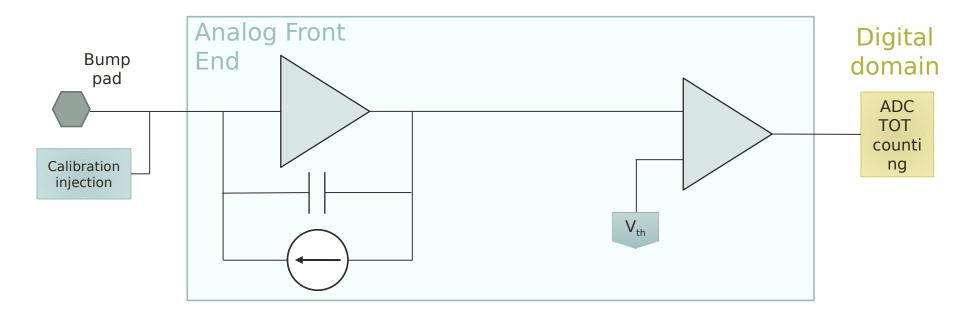
Calibration injection circuit

- Present in each pixel, picks charge from global voltage sources
- Same across the whole chip
- Equivalent to 2 switches
 - controlled by 2 control signals (S0 and S1)
 - switching between 3 voltage levels (CAL_HIGH, CAL_MED and GND)

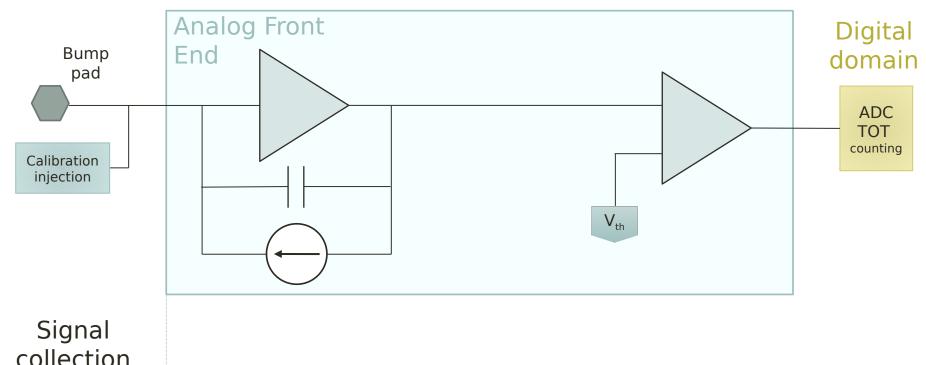
→ injection of a known charge to pixels







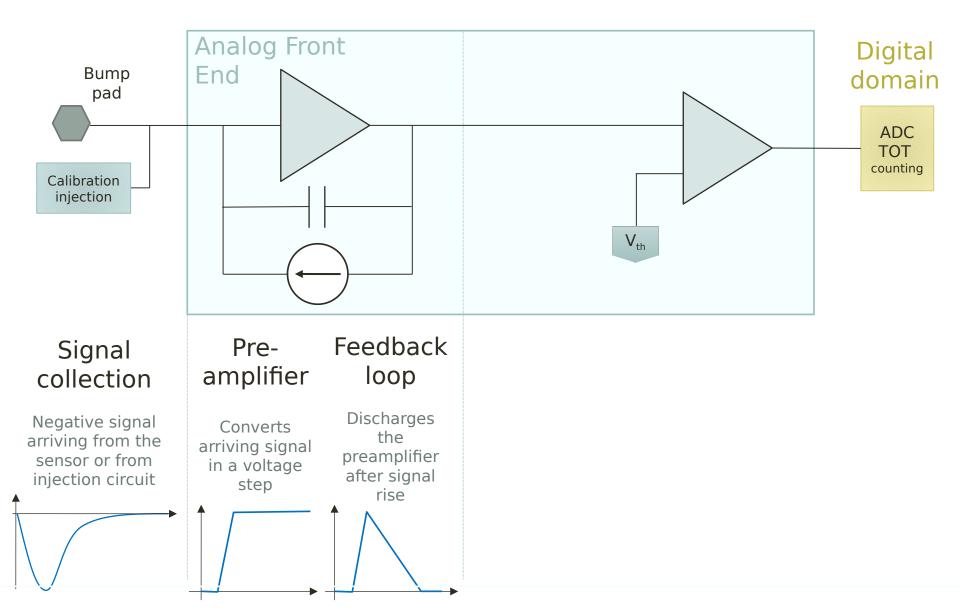




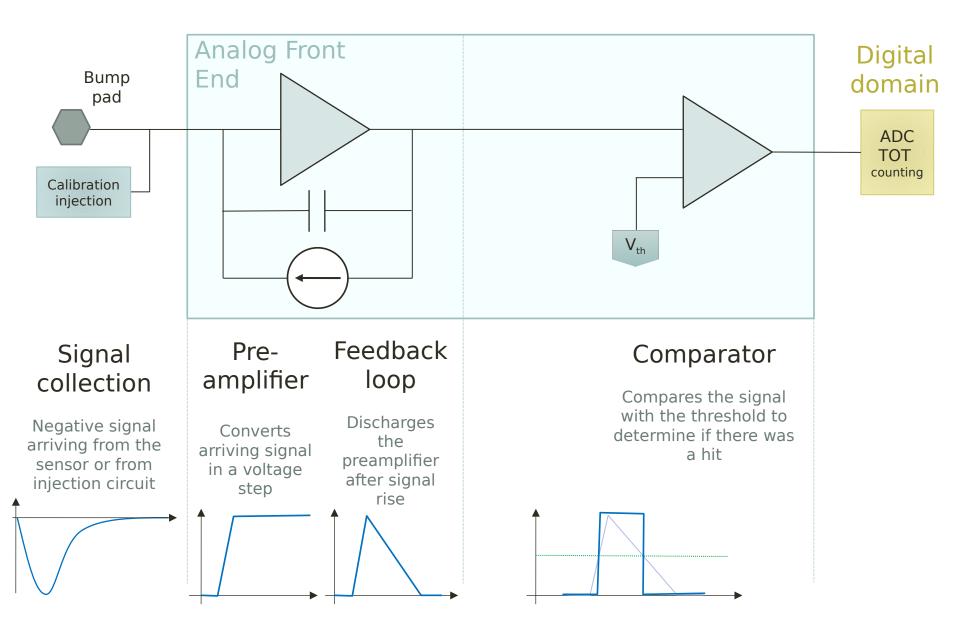
collection

Negative signal arriving from the sensor or from injection circuit

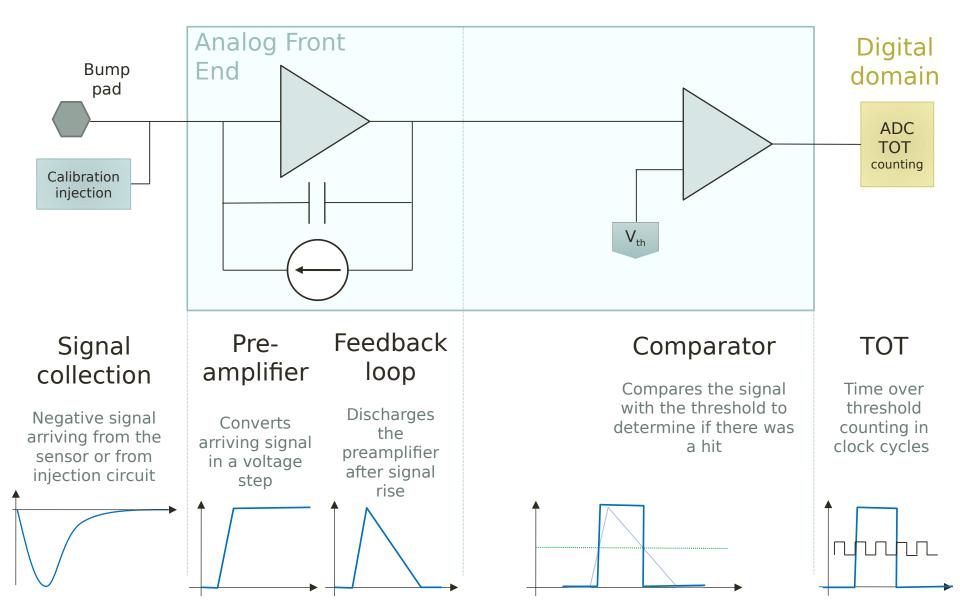




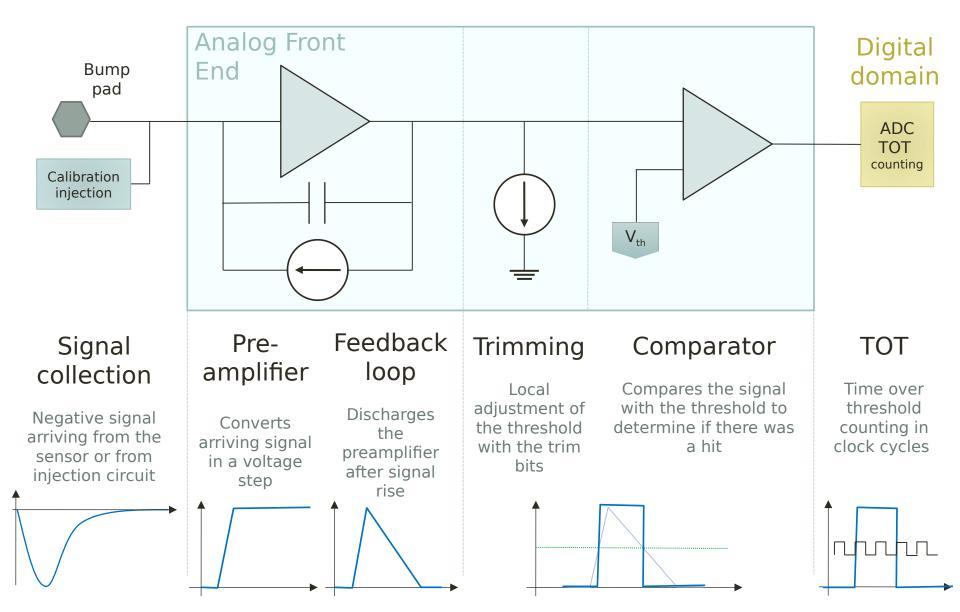








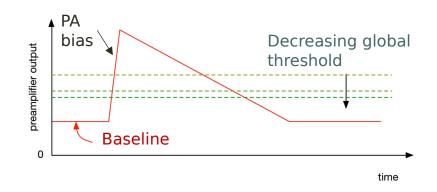


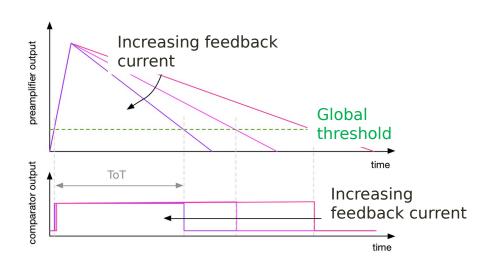


ANALOG FRONT-END PARAMETERS



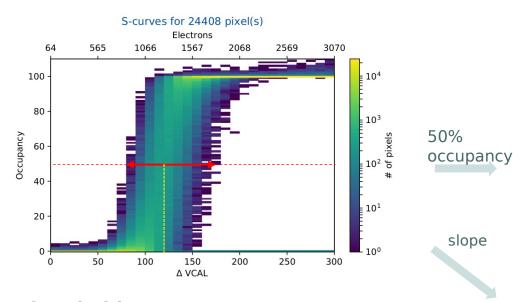
Global threshold	Sets the global threshold of the comparator
Baseline voltage	Sets the preamplifier output DC baseline
Preamplifier bias	Determines the speed of rise of the signal, main contribution to the power consumption, influence on the noise
Feedback current	Determines the speed of the preamplifier return to baseline and therefore the time over threshold





TUNING PROCEDURES





Threshold scan

Inject different charges, 100x to every pixel and check number of hits \rightarrow occupancy

S-curves

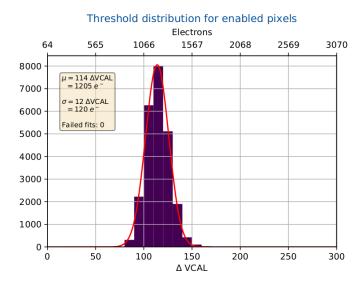
Occupancy vs. injected charge, for every pixel

Threshold

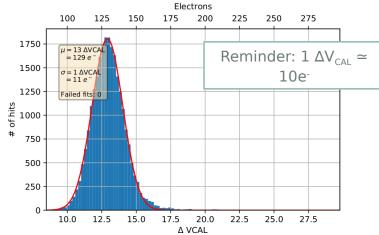
Charge at which 50% occupancy is reached, for every pixel

Equivalent noise charge (ENC)

Slope of the s-curve, for each pixel





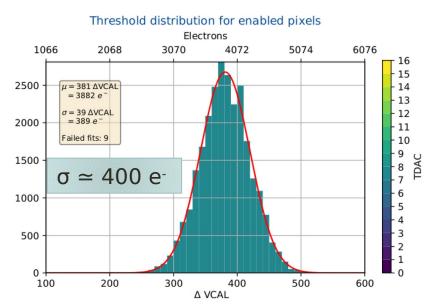


THRESHOLD TRIMMING



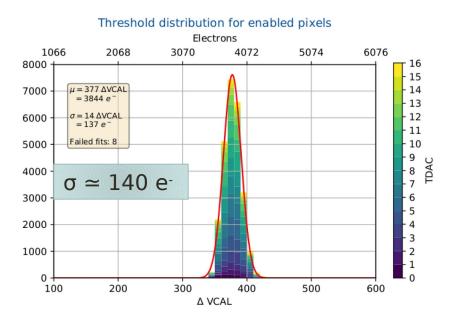
• per pixel local compensation of comparator threshold dispersion

set a register in each pixel with a number of trimming bits
 needed to bring local threshold as close as possible to the mean threshold



Before tuning

- All trim bits set to 7
- Wide threshold distribution



After tuning

- Each pixel with a different trim bit (7 as average trim)
- Narrow threshold distribution